OptiMOS™-5 Power-Transistor

AEC Qualified RoHS

Features

- OptiMOS™ - power MOSFET for automotive applications
- N-channel - Enhancement mode - Normal Level
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green product (RoHS compliant)
- 100% Avalanche tested

Quality Features

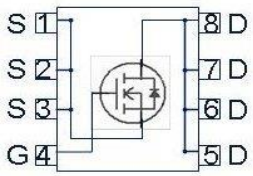
- Infineon Automotive Quality
- Extended qualification beyond AEC Q101
- Enhanced testing
- Advanced adhesion against delamination
- Complementary testing for board level reliability

Advanced adhesion Robust Enhanced tested

Product Summary

V_{DS}	80	V
$R_{DS(on)}$	10	mΩ
I_D	40	A

PG-TSDSON-8



Type	Package	Marking
IAUZ40N08S5N100	PG-TSDSON-8	5N08100

Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continous drain current	I_D	T_C=25°C, V_{GS}=10V[1)]	40	A
		T_C=100 °C, V_{GS}=10 V[2)]	40	
Pulsed drain current[2)]	$I_{D,pulse}$	T_C=25°C	160	
Avalanche energy, single pulse[2)]	E_{AS}	I_D=20 A	75	mJ
Avalanche current, single pulse	I_{AS}	-	32	A
Gate source voltage	V_{GS}	-	±20	V
Power dissipation	P_{tot}	T_C=25 °C	68	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics[2]						
Thermal resistance, junction - case	R_{thJC}	-	-	-	2.2	K/W
Thermal resistance, junction - ambient[3]	R_{thJA}		-	38.5	-	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=1 mA	80	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=27 µA	2.2	3	3.8	
Zero gate voltage drain current	I_{DSS}	V_{DS}=80 V, V_{GS}=0 V, T_j=25 °C	-	-	1	µA
		V_{DS}=80 V, V_{GS}=0 V, T_j=85 °C[2]	-	-	100	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=6 V, I_D=10 A	-	11.6	14.5	mΩ
		V_{GS}=10 V, I_D=20 A	-	8.4	10	
Gate resistance[2]	R_G		-	1.2	-	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics[2]						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz	-	1224	1591	pF
Output capacitance	C_{oss}		-	231	300	
Reverse transfer capacitance	C_{rss}		-	13.5	20	
Turn-on delay time	$t_{d(on)}$	V_{DD}=40 V, V_{GS}=10 V, I_D=40 A, R_G=3.5 Ω	-	3	-	ns
Rise time	t_r		-	1	-	
Turn-off delay time	$t_{d(off)}$		-	7	-	
Fall time	t_f		-	5	-	
Gate Charge Characteristics[2]						
Gate to source charge	Q_{gs}	V_{DD}=40 V, I_D=20 A, V_{GS}=0 to 10 V	-	5.8	7.5	nC
Gate to drain charge	Q_{gd}		-	4.5	6.8	
Gate charge total	Q_g		-	18.6	24.2	
Gate plateau voltage	$V_{plateau}$		-	4.8	-	V
Reverse Diode						
Diode continous forward current[2]	I_S	T_C=25 °C	-	-	40	A
Diode pulse current[2]	$I_{S,pulse}$		-	-	147	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=20 A, T_j=25 °C	-	0.9	1.2	V
Reverse recovery time[2]	t_{rr}	V_R=40 V, I_F=40A, di_F/dt=100 A/µs	-	37	-	ns
Reverse recovery charge[2]	Q_{rr}		-	32	-	nC

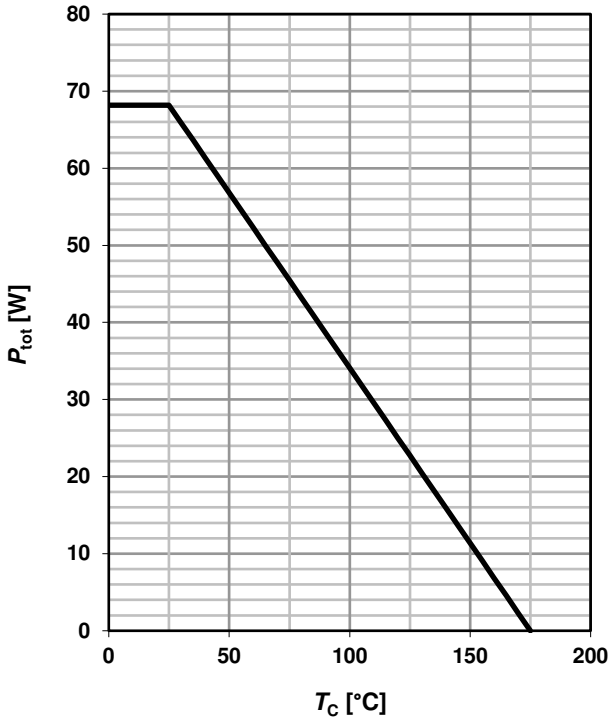
[1] Current is limited by bondwire; with an R_{thJC} = 2.2 K/W the chip is able to carry 58A at 25°C.

[2] The parameter is not subject to production test - verified by design/chracterization.

[3] Device on four layer 2s2p PCB defined in accordance with JEDEC standards (JESD51-5-7). PCB is vertical in still air.

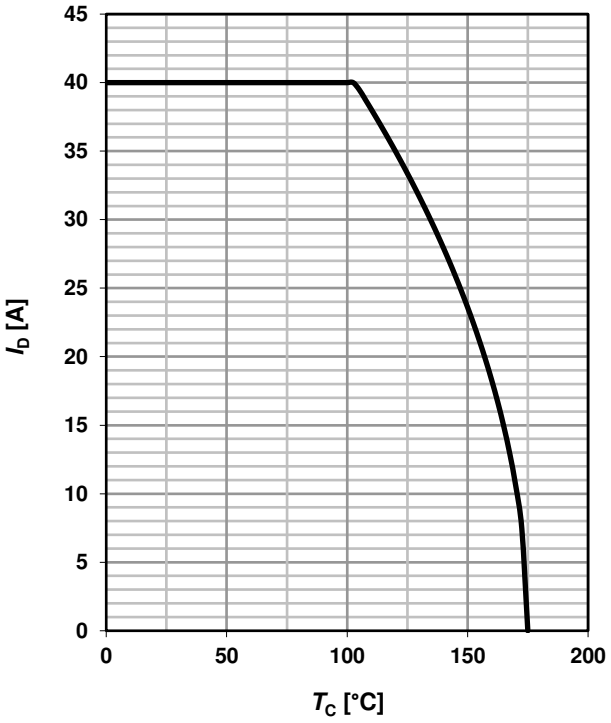
1 Power dissipation

$P_{tot} = f(T_C)$; $V_{GS} \geq 6$ V



2 Drain current

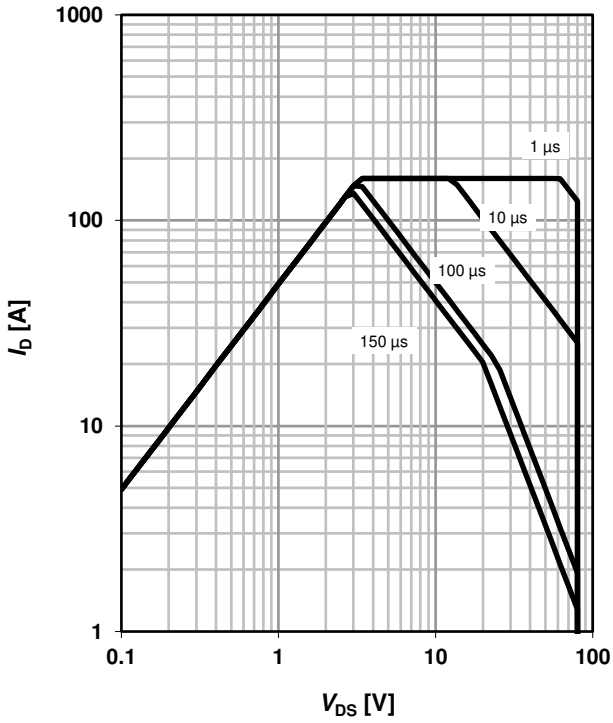
$I_D = f(T_C)$; $V_{GS} \geq 6$ V



3 Safe operating area

$I_D = f(V_{DS})$; $T_C = 25$ °C; $D = 0$

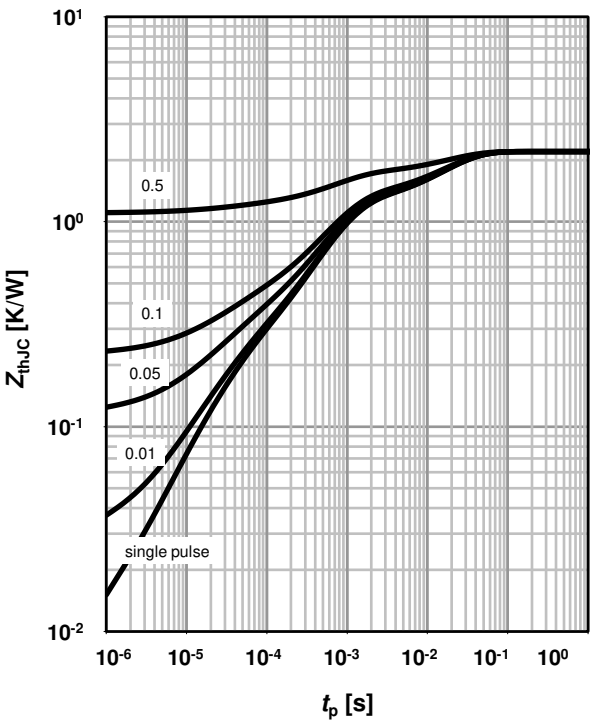
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

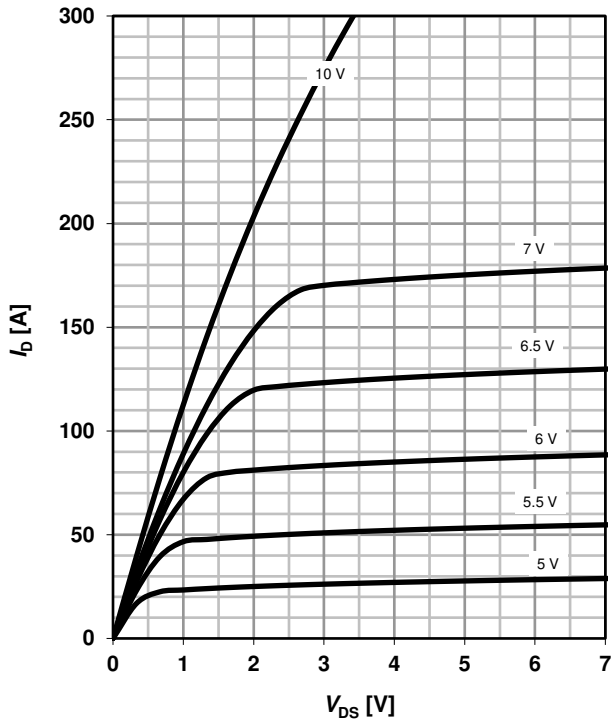
parameter: $D = t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25$ °C

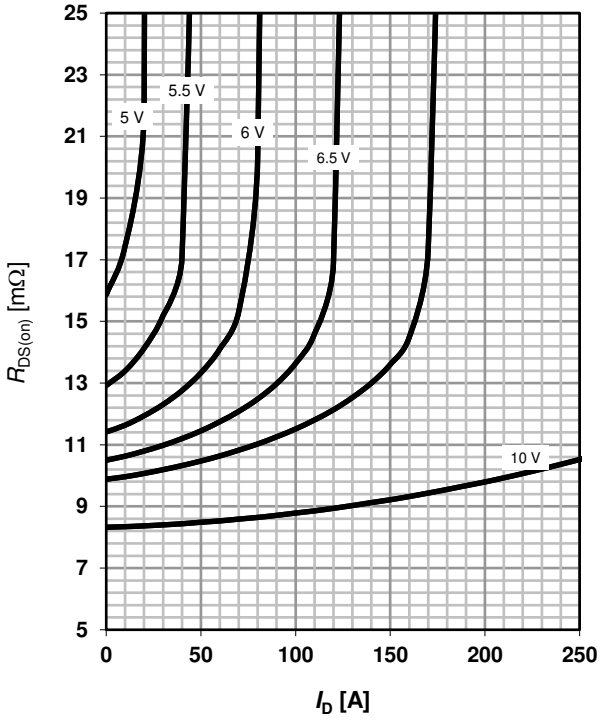
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = (I_D)$; $T_j = 25$ °C

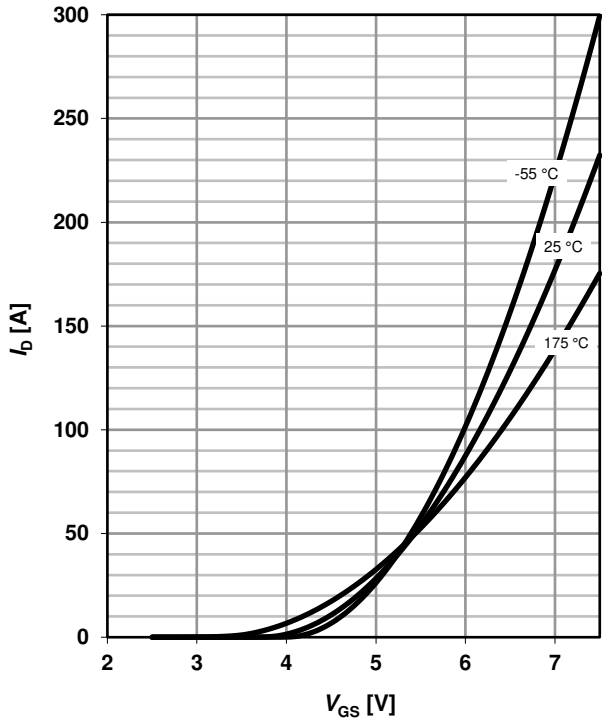
parameter: V_{GS}



7 Typ. transfer characteristics

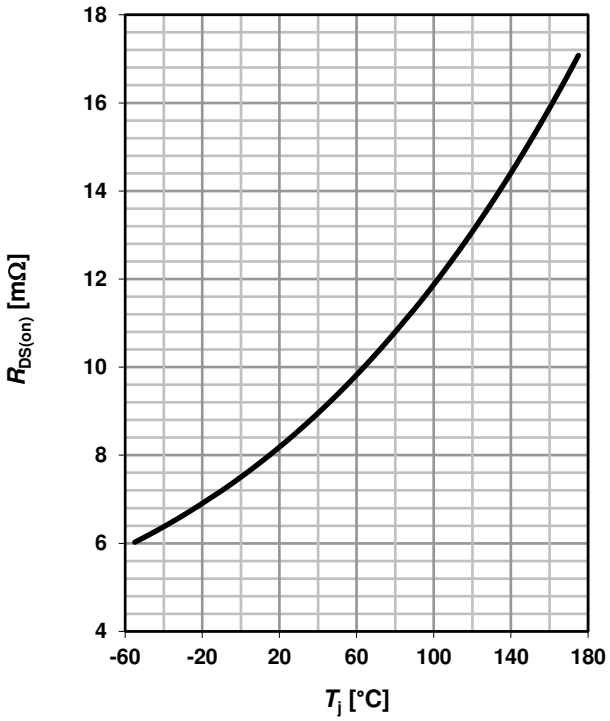
$I_D = f(V_{GS})$; $V_{DS} = 6$V

parameter: T_j



8 Typ. drain-source on-state resistance

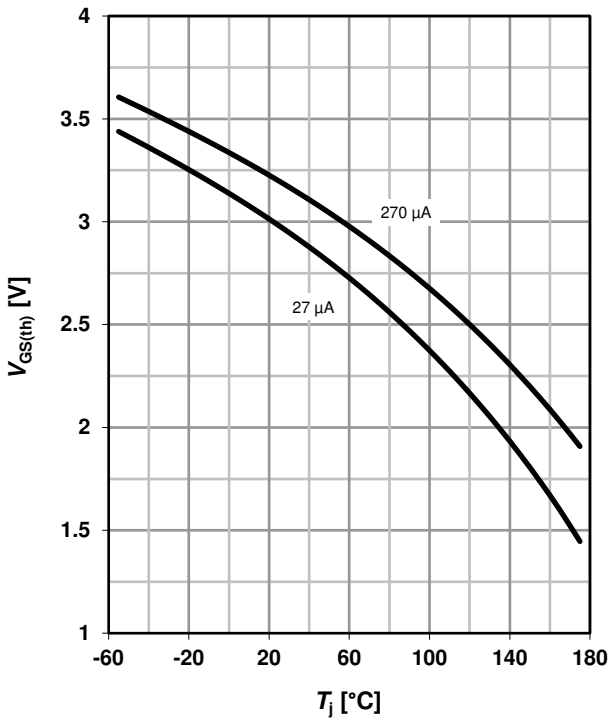
$R_{DS(on)} = f(T_j)$; $I_D = 20$ A; $V_{GS} = 10$ V



9 Typ. gate threshold voltage

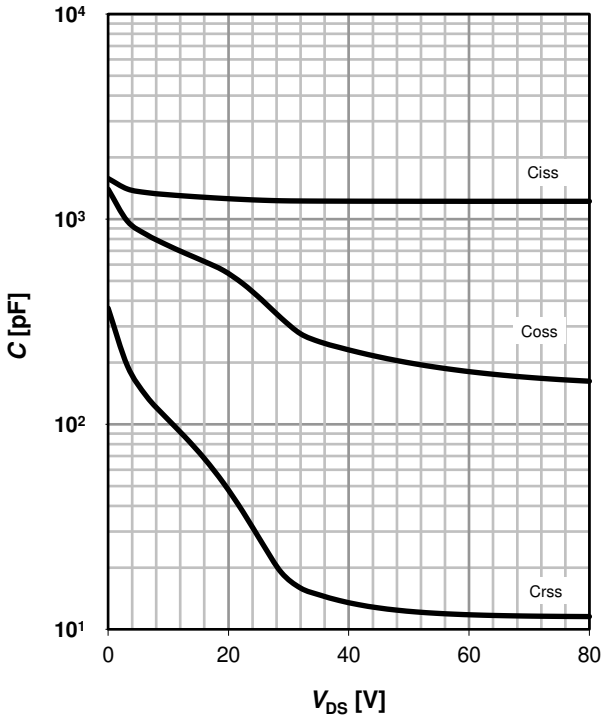
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

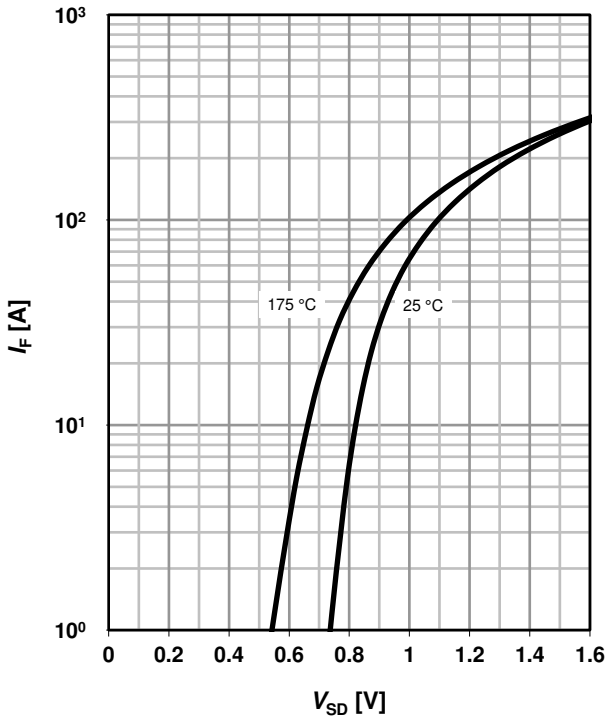
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz



11 Typical forward diode characteristicis

IF = f(V_{SD})

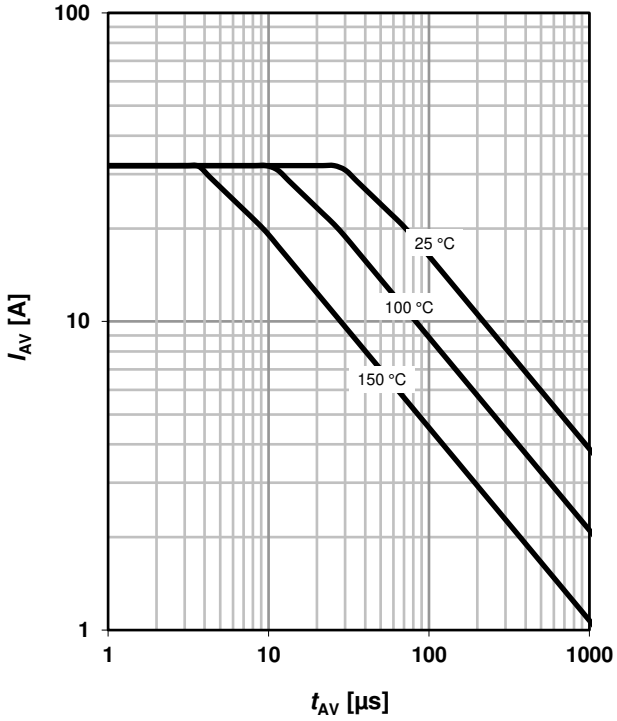
parameter: T_j



12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$

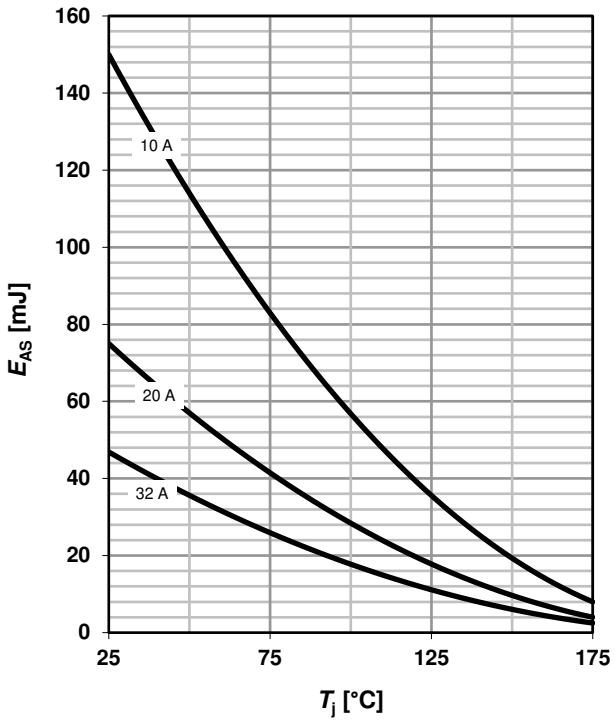
parameter: $T_{j(start)}$



13 Typical avalanche energy

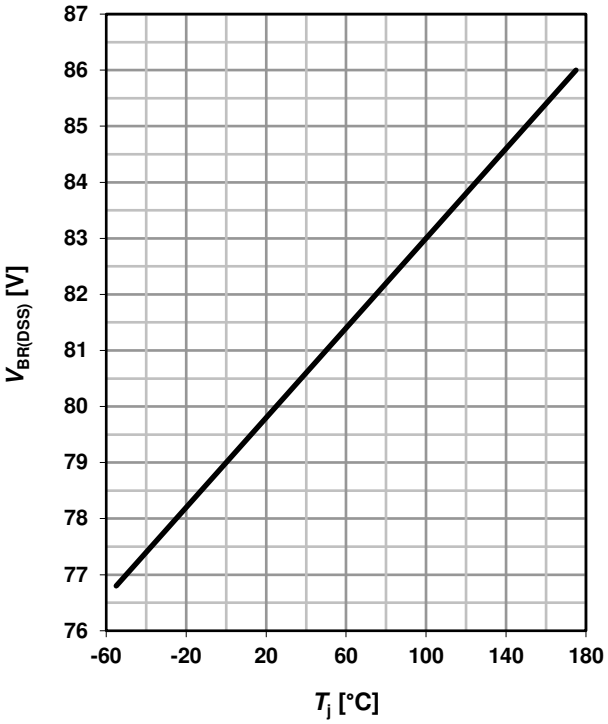
$E_{AS} = f(T_j)$

parameter: I_D



14 Drain-source breakdown voltage

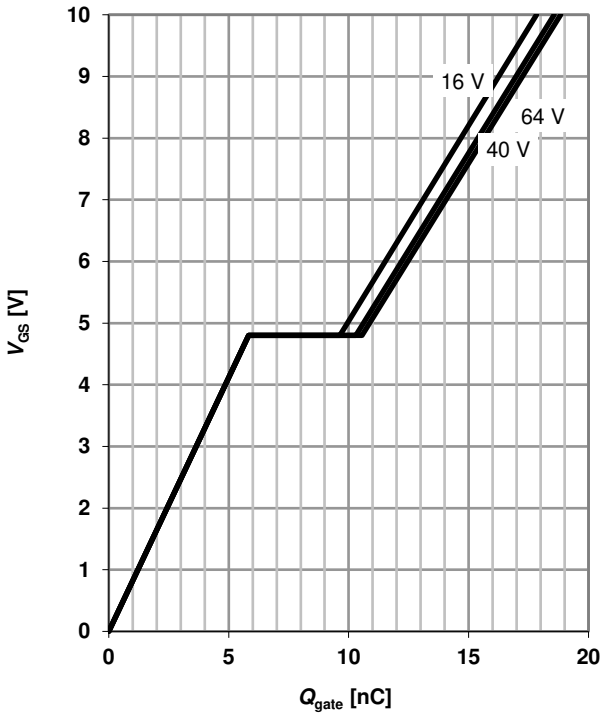
$V_{BR(DSS)} = f(T_j)$; $I_{D\_typ} = 1$ mA



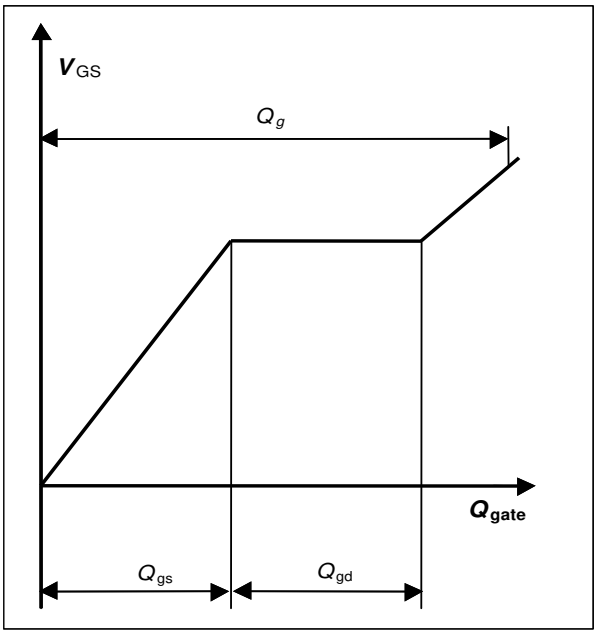
15 Typ. gate charge

$V_{GS} = f(Q_{gate})$; $I_D = 20$ A pulsed

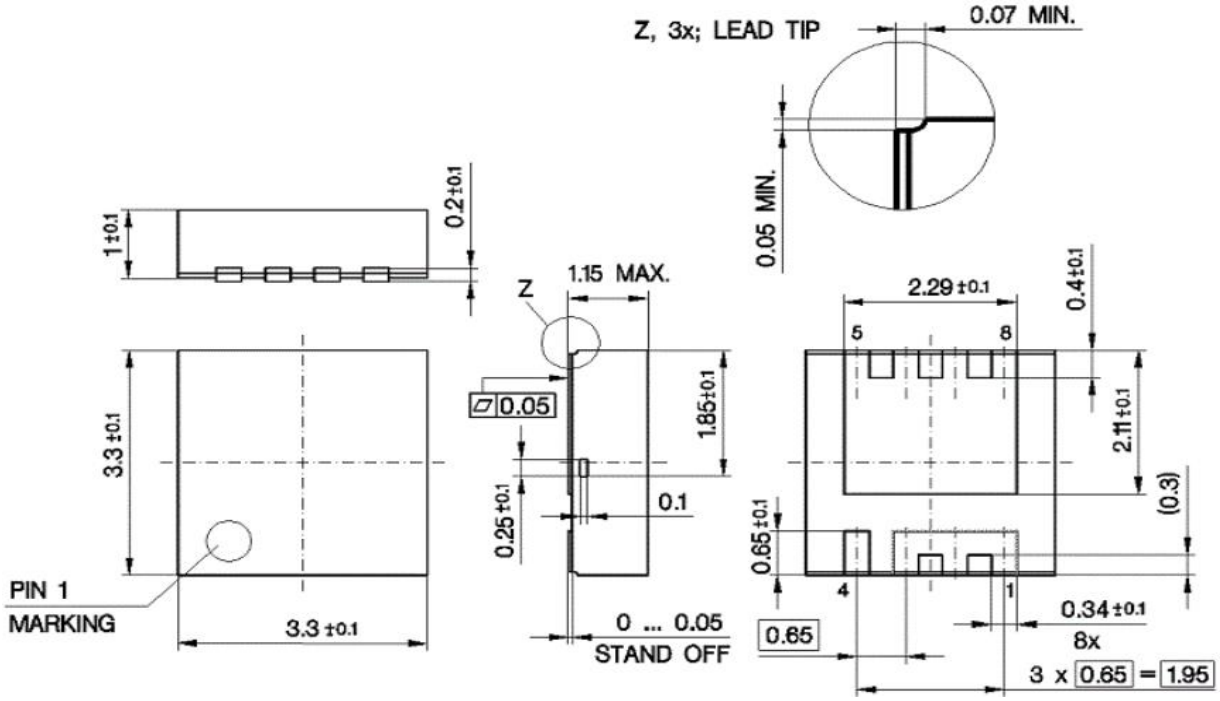
parameter: V_{DD}



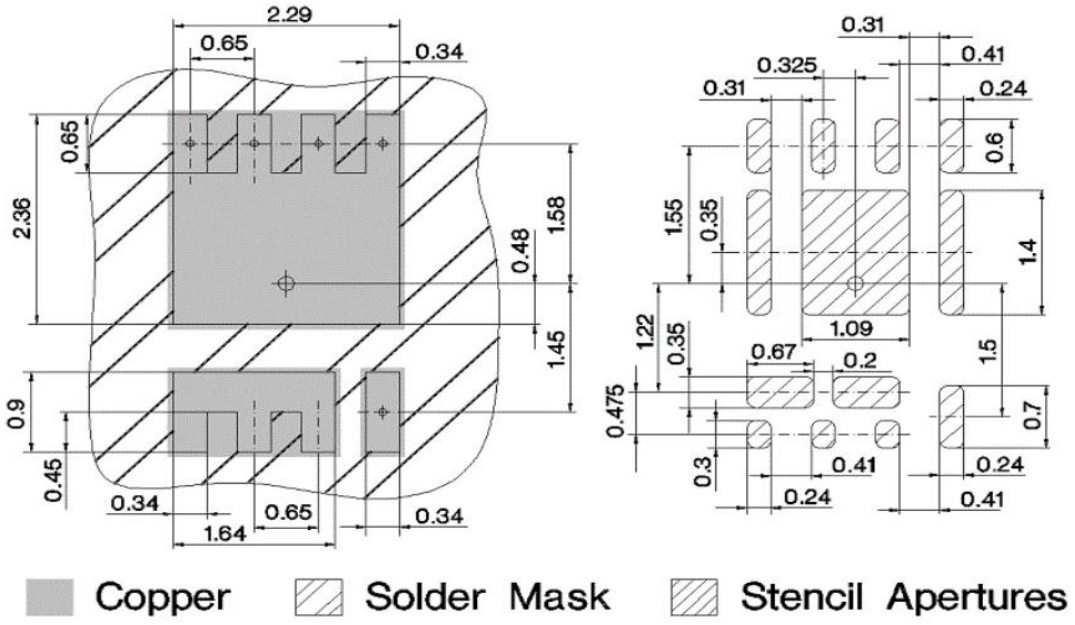
16 Gate charge waveforms



PG-TSDSON-8: Outline

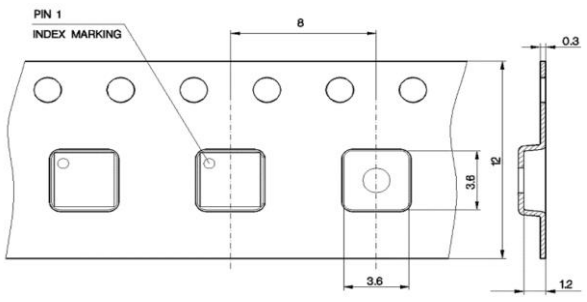


Footprint



Dimensions in mm

Packaging



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